



Final Product Change Notification

201506028F01

Issue Date: 14-Oct-2015
Effective Date: 28-Jan-2016

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QUALITY

Management Summary

As part of the NXP Business Continuity Management (BCM) program it has been decided to establish Dual Sourcing for TDF8546, TDF8546A & TDF8548A.

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input checked="" type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling

Introduction of a dual source - TDF8546, TDF8546A, TDF8548A

Details of this Change

As part of the NXP Business Continuity Management (BCM) program it has been decided to establish Dual Sourcing for TDF8546, TDF8546A & TDF8548A. The following changes are applied:

1. The diffusion fab of TDF8546, TDF8546A & TDF8548A will have a 2nd location of wafer fab VIS, Taiwan, in parallel to the current running production in wafer fab ICN8 (Nijmegen, The Netherlands).
2. Two sourcing combinations will be qualified and are planned to be delivered to the market:
 - a. VIS-APK
 - b. ICN8-APK; qualified and released for production.
The actual sourcing is finally at NXP's discretion
3. Metal layer thickness of VIS is upgraded to Ti/NiV/Ag=100/300/600 (from ICN8 Ti/NiV/Ag=100/500/100) to use the latest technology with rougher surface which leads to improved metal adhesion and requires improved coverage of the NiV layer. After Die bonding (soldering of die on the heat slug) product are the same again
4. A new 12NC is defined for all dual source types (see new product 12NC overview).
5. The marking on the IC (see Identification of Affected Products section) will change accordingly

The mentioned changes will not imply any change in product, fit, form and function (no change in specification!!)
R-Gate samples will be available from 02 November 2015.

Why do we Implement this Change

1. Support continuous customer deliveries in case of major natural disasters / significant business interruptions
2. To meet customers demand and support future growth by increasing flexibility and capacity
3. Align with world-class technology trends

Identification of Affected Products

Top side marking

Marking on the IC will be as follows:

1. 3rd line depending on the waferfab source
2. "r" : Waferfab VIS, Taiwan
3. "T": Waferfab ICN8, The Netherlands

Product Availability

Sample Information

Samples are available from 02-Nov-2015

Production

Planned first shipment 30-Nov-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 12-Nov-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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